

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re the Appl	cation of: Jitaru
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Serial #:

09/434,985 11/05/99

Docket #:

1675B.1A.1

Filed:

Examiner: Group:

For:

Low Noise Full Integrated Multilayers Magnetic For Power

Converters

2800 MAIL ROOF

FEE CALCULATION FOR THIRD PRELIMINARY AMENDMENT

Honorable Commissioner of Patents and Trademarks Washington D.C. 20231

Sir:

Payment is based on the following calculations (37 C.F.R. 1.16):

CURRENT NUMBER OF INDEPENDENT CLAIMS NUMBER OF INDEPENDENT CLAIMS PREVIOUSLY PAID Excess:

(X) Small Entity @ \$39.00 each

( ) NOT Small Entity @ \$78.00 each

CURRENT NUMBER OF CLAIMS NUMBER OF CLAIMS PREVIOUSLY PAID

\$ 81.00

(X) Small Entity @ \$9.00 each

( ) NOT Small Entity @ \$18.00 each

CURRENT NUMBER OF MULTIPLE DEPENDENT CLAIMS NUMBER OF MULTIPLE INDEPENDENT CLAIMS PAID

Excess

Excess

(X) Small Entity @ \$130.00

( ) NOT Small Entity @ \$260.00

TOTAL:

\$ 120.00

Respectfully Submitted,

Mark E. Odram Attorney at Law Reg. No. 30343

CERTIFICATE OF MAILING (37 CFR 1.8)

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on 7, 1990

reg. no. 30343

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THIRD PRELIMINARY AMENDMENT

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JUN - 6 2000

Sir:

Regarding the above identified patent application, please make the following amendments and note the corresponding remarks.

## Enclosures:

(1) FEE CALCULATION sheet;

(2) Check number 3533 for the amount \$120.00.

In the Claims:

Add the following claims 24-3

-- The power processing device according to claim 22, further including an active element secured to said multilayered printed circuit board and connected to the first set of electrically conductive windings. --

- - 25. The power processing device according to claim 24, further including:

- a) a heat sink connected to one face of said multilayered printed
- 4 circuit board opposing said active element; and,
  - b) a thermal via thermally connecting said active element and the heat

6 sink. - -

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